SHENMAO TECHNOLOGY

Your Ultimate Choice For Solder!!

No-Clean Lead-Free ,Halide-Free Solder Paste

Model: PF606-P26

Rev.2015/12/30 Ver.05-00

—Specification—

Item	Specification	Standard
Appearance	Gray paste w/o visible foreign and clusters	
Alloy composition	Sn/Ag3.0/Cu0.5/X	JIS-Z-3282
Melting Point	217~219°C	
Particle Size	(Type 3) +45μm ＜1%，—20μm ＜10% (Type 4) +38μm ＜1%，—20μm ＜10% (Type 5) +25μm ＜1%，—15μm ＜10% (Type 6) +15μm ＜1%，— 5μm ＜10%	
Powder Shape	Spherical	
Flux Content	12.0±1.0wt.%	JIS-Z-3197, 8.1.2
Viscosity	200±30 Pa · s (25±1°C, 10rpm, Malcom)	JIS-Z-3284, Annex 6
Flux Type	ROL0	J-STD-004

—Test Content—

Test Item	Test Result	Test Method
Copper Plate Corrosion Test	Pass	IPC-TM-650, 2.6.15
Halogen Content Test	ROL0	BS EN14582
Copper Mirror Test	Pass	IPC-TM-650, 2.3.32
Viscosity Test (25°C,10rpm)	200±30 Pa · s	JIS-Z-3284, Annex 6
Spreading Test	>70%	JIS-Z-3197, 8.3.1.1
Tackiness Test (gf)	>130(8hr)	JIS-Z-3284, Annex 9
Slump Test	Pass	JIS-Z-3284, Annex 7, 8
Solder Ball Test	Pass	JIS-Z-3284, Annex 11

—Reliability Test—

Test Item	Test Result	Test Method
S.I.R. Test ▲	Pass	IPC-TM-650, 2.6.3.3
Electro Migration Test ◆	Pass	IPC-TM-650, 2.6.14.1

▲*Test Conditions：85°C, 85% RH for 168 hrs*

◆*Test Conditions：65°C, 88.5% RH for 596 hrs*

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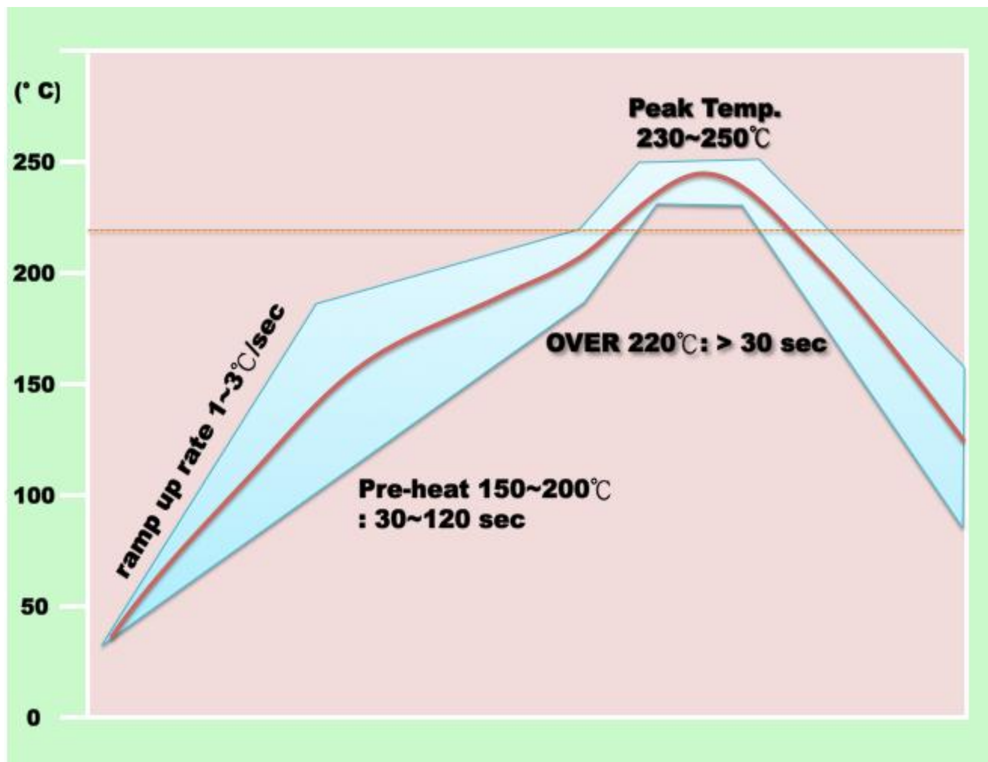
—Alloy Composition—

Sn	Ag	Cu	Ni	Ge	Zn	Al	Sb	Fe	As	Bi	Cd	Au	In	Pb
REM.	2.8~ 3.2	0.3~ 0.7	0~ 0.01	0~ 0.01	0.001 Max	0.001 Max	0.05 Max	0.02 Max	0.03 Max	0.10 Max	0.002 Max	0.05 Max	0.10 Max	0.05 Max

Patent No.: Japanese Patent No. 3296289 U.S Patent No. 6179935B1. Germany Patent No.19816671C2. (wt.%)

All alloy of SHENMAO' products were to conform to SONY Green Partner and comply RoHS requirement.

—Temperature Profile—



The recommended reflow profile for the PF606-P26 is provided as a guideline. Optimal profile may differ due to oven type,assembly layout,or other process variables.

Ramp Up Rate (30~150°C):	**1.0~3.0 °C/sec**
Pre-heating Time (150~200°C) :	**30~120 sec**
Time Period Above 220°C:	**>30 sec**
Peak Temperature:	**230~250 °C**
Ramp Down Rate During Cooling:	**1.0~6.0 °C/sec**

—Handling and Storage Instructions—

1. Storage

(1) Refrigerate pastes at 0~10 °C helps prolong shelf life; normal shelf life is 6 months from production date (sealed jars).
(2) Keep away from direct sunlight.

2. Operation Manual (Sealed)

(1) Allow pastes to reach ambient printing temperature(22-28°C) prior to use for 3 - 4 hrs. Do not heat to raise temperature abruptly.
(2) Well mix paste with plastic spatula for 1-3 mins before use. Mixing time depends on tool type.

3. Operation Manual (Opened)

(1) At first, add 2/3 jar of solder paste onto the stencil. Do not add more than 1 jar.
(2) Add a little amount of paste at a time on the stencil according to printing speed.
(3) It is recommended to finish fresh paste within 24 hrs. To maintain paste quality, make sure not to store used paste and fresh paste in the same jar.
(4) After printing, it is suggested to place components to be mounted on the circuit board and reflow within 4 – 6 hrs.
(5) If printing process was interrupted for more than 1 hr, be sure to remove paste remnant from stencil and seal them in the jar.
(6) It is recommended to keep printing environment at 22~28 °Cand RH of 30~60%.
(7) To clean up printed circuit boards, it is suggested to use ethanol or isopropanol.

Contact Information

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